

Application Data Sheet

Application Information

Application Type:: Regular
Subject Matter:: Utility
CD-ROM or CD-R?:: None
Computer Readable Form (CRF)?:: No
Title:: METHOD OF MANUFACTURING A FLIP-CHIP SEMICONDUCTOR DEVICE WITH A STRESS-ABSORBING LAYER MADE OF THERMOSETTING RESIN
Attorney Docket Number:: 067123-0195
Request for Early Publication?:: No
Request for Non-Publication?:: No
Suggested Drawing Figure::
Total Drawing Sheets:: 37
Small Entity?:: No
Petition included?:: No
Secrecy Order in Parent Appl.?:: No

Applicant Information

Applicant Authority Type:: Inventor
Primary Citizenship Country:: Japan
Status:: Full Capacity
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Correspondence Information

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Representative Information

Representative Customer Number::	22428	
Number::		

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Division of	09/704,521	11/03/2000

Foreign Priority Information

Country::	Application number::	Filing Date::	Priority Claimed::
Japan	11-313684	11/04/1999	Yes

Assignee Information

Assignee name :: NEC Electronics Corporation